conductive member electrically connecting said first electrically conductive member and each of said plurality of electrode pads.

REMARKS

The drawings are objected to as failing to comply with 37 CFR 1.84(p)(5). Applicants have amended the specification to reflect that FIGs. 12A and 12B have been changed to FIGs. 20A and 20B. No amendments to the Figures are necessary.

Claim 19 is rejected under 35 USC §112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter. In response thereto, Applicants have amended claim 19 to address the issues raised by the Examiner. Accordingly, all of the claims are now deemed to be in compliance with 35 USC §112.

Claims 13-15, 17, and 20 are rejected under 35 USC §103 as obvious over Morishima, US Patent Publication 20010011857, in view of Kobayashi et al., US Patent No. 5,311,402.

Independent claim 13 recites a second substrate closely adhered to the other face of the sealing wall. Likewise, the second substrate has a plurality of openings at sites confronting the plurality of electrode pads.

Morshima '857 describes a surface acoustic wave device that is small, lightweight, and highly reliable, and protects its functional portion. The surface acoustic wave device has surface acoustic wave elements mounted on a circuit substrate. Each substrate acoustic wave element includes a frame like first insulating film furnished to surround functional portions on a chip. A lid-like second insulating film is deposited on the first insulating film so as to cover

driving electrodes and surface wave propagation paths of the functional portions, while securing a hollow portion over the functional portions.

Kobayashi et al. '402 describes a semiconductor having an IC chip package on a circuit board, and a cap for hermetically sealing the chip. The cap is bonded to the circuit board at the edges of an open end thereof, and bonded to the chip at the underside or bottom thereof. To accurately position the chip on the circuit board, the circuit board is provided with a groove or a shoulder in a position where it faces the edges of the open end of the cap. After the chip has been positioned on the circuit board, the cap is bonded to the circuit board via the groove or the shoulder.

Morishima '857 does not teach or suggest a second substrate having a plurality of openings at sites where bonding occurs, as stated by the Examiner. Instead, the openings in the substrate disclosed in Kobayashi et al. '402 are concave grooves for adjusting the depth at which the legs of sealing caps are inserted, and completely differ from the openings of the invention through which the electrically conductive member extends.

Accordingly, the combination of Morishima '857 and Kobayashi et al. '402 does not render obvious independent claim 13.

As to claims 14-15, 17, and 20, they are dependent on claim 13, respectively. Therefore, claims 14-15, 17, and 20 are also allowable for the same reasons argued with respect to claim 13.

In view of the above amendments and for all the reasons set forth above, the Examiner is respectfully requested to reconsider and withdraw the objections and rejection made under

35 U.S.C. §§ 103 and 112, second paragraph. Accordingly, an early indication of allowability is earnestly solicited.

If the Examiner has any questions regarding matters pending in this application, please feel free to contact the undersigned below.

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page is captioned **"VERSION WITH MARKINGS TO SHOW CHANGES MADE"**.

Respectfully submitted,

Reg. No. 47,251

Matthew E. Connors
Registration No. 33,298
Samuels, Gauthier & Stevens
225 Franklin Street, Suite 3300
Boston, Massachusetts 02110
Telephone: (617) 426-9180
Extension: 112

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE SPECIFICATION

Paragraph beginning at page 2, line 5 has been amended as follows:

-- Referring to FIGs. ~~12A~~ 20A and ~~12B~~20B, an electronic component is shown having a structure that is disclosed in "Optimizing AQP SAW Resonators for Reduced Vibration Sensitivity" published in IEEE Ultrasonic Symposium, 1995. FIG. 12A is a side elevation of an electronic component 110; and FIG. 12B is a sectional view of the same taken along a line A-A of FIG. 12A. The electronic component 110 is an SAW resonator. The SAW resonator includes comb-shaped electrodes 116, 118, 120 and 122 that are formed on a main surface 114 of an SAW substrate 112. A glass sealing wall 126 is formed on a quartz substrate 124 and is fused to the main surface 114 of the SAW substrate 112. The sealing wall 126 is formed so as to enclose an SAW device formed on the SAW substrate 112. The SAW device is hermetically sealed by the SAW substrate 112, quartz substrate 124 and sealing wall 126. The comb-shaped electrodes 116, 118, 120 and 122 extend beyond the sealing wall 126 so that their extremities, i.e., electrodes pads 128, 130, 132 and 134 are connected via bonding wires not shown to a circuit board not shown. In the step of assembling such two substrates into the electronic component 110, the assembly is typically carried out for each electronic component.--

Paragraph beginning at page 5, line 25 has been amended as follows:

-- When fabricating the electronic component 110 depicted in FIGs. ~~12A~~ 20A and ~~12B~~20B, the sealing wall 126 may be heated upon fusing of the sealing wall 126 made of glass, polyimide resin or epoxy resin onto the main surface 114 of the SAW substrate 112, with the result that gas may be generated at the sealing wall fused portion. The thus generated gay may possibly attach to the SAW device electrodes inside the sealing wall, resulting in degradation of the SAW device characteristics.--

IN THE CLAIMS

Claims 19 has been amended as follows:

19 (Amended). A method of manufacturing an electronic component according to claim 13, wherein

a first electrically conductive member is ~~previously~~ formed on an inner wall of each of said plurality of openings, said first electrically conductive member being electrically connectable to said circuit board, and wherein

said second step includes a step in which, a second electrically conductive member is formed on each of said plurality of electrode pads, said second electrically conductive member electrically connecting said first electrically conductive member and each of said plurality of electrode pads.